

1999-341860/29 L03 M13
SUMITOMO SPECIAL METALS CO LTD
 1997.10.15 1997-299502(+1997JP-299502) (1999.05.11) C23C 18/31,
 B22F 1/02, H01L 21/60
Conductive film plating to micro plastic ball used on bump electrode in semiconductor package - involves using rotatable plating tank for repeated inversion of ball, contacting cathode provided at periphery
C1999-101040

NOVELTY

A horizontal flat rotary plating tank (3), bears cathode (4) and anode (6) on its periphery and centre, respectively. Plating liquid is fed to tank which is rotated vertically at 50 - 800 rpm. Micro plastic balls of 1 mm or less of diameter, fed to the tank, are contacted to cathode with repeated inversions to form metal or alloy conductive film of thickness 0.5-5 μm .

USE

To form conductive film on micro plastic ball used on bump electrode in semiconductor package.

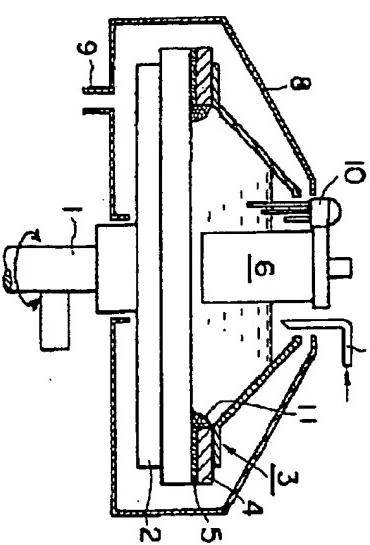
ADVANTAGE

SUMS 1997.10.15
 *JP 11124682-A
 L(4-C10, 4-C11) M(i3-B)

Obtains high efficiency plating with highly precise uniform solder film.

DESCRIPTION OF DRAWING(S)

e figure shows vertical section explanatory drawing of plating apparatus. (3) Rotary plating tank; (4) Cathode; (6) Anode.



(5pp3036DwgNo.1/2)

| JP 11124682-A